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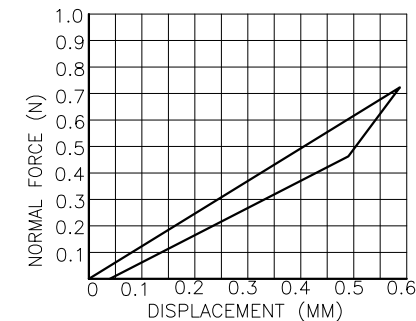
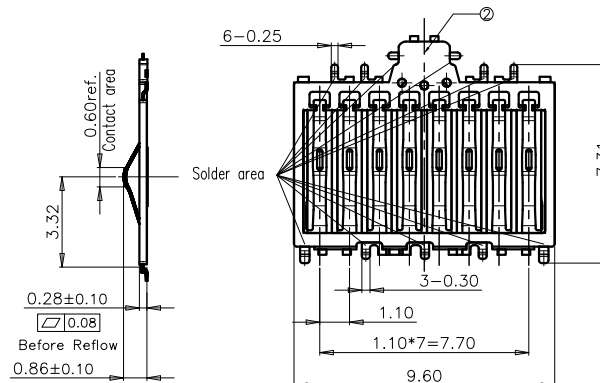
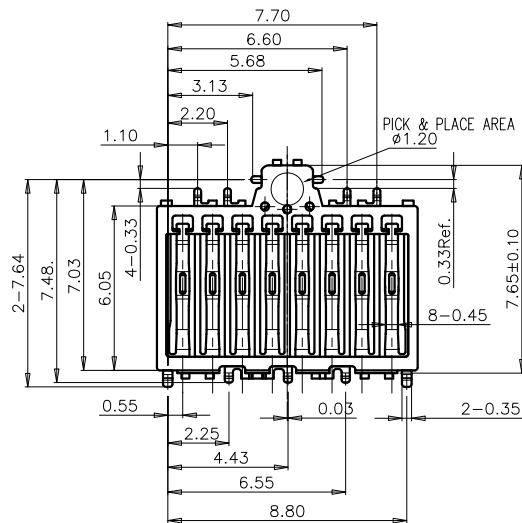
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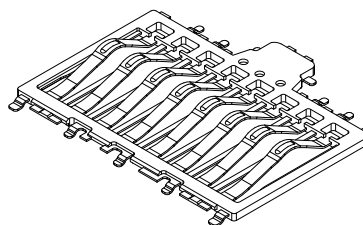
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REV.	ECN NO OR DESCRIPTION	REVISED	DATE
▽	PROPOSE ONLY	ALLEN	2015.05.23
▽	修改端子头部与塑胶的结合方式	ALLEN	2019.12.08



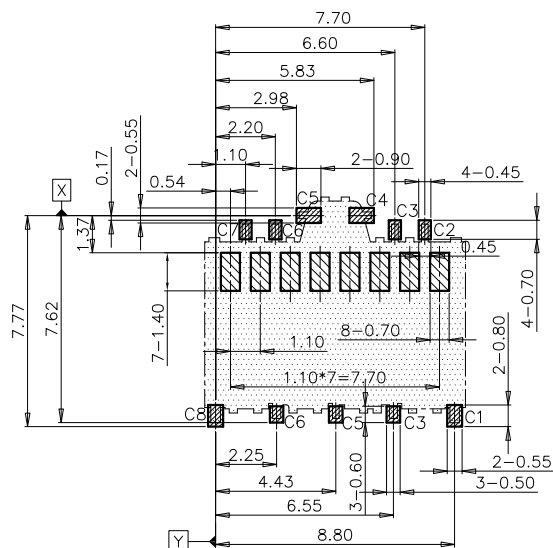
- NOTES:
1. MATERIAL:SEE TABLE 1.
 2. SPECIALITY:
 - 2.1 Rated current:0.5A Max
 - 2.2 Rated voltage:10V DC
 - 2.3 Contact Resistance:60mΩ MAX
 - 2.4 Insulation Resistance:1000MΩ MIN 500V DC
 - 2.5 Dielectric withstanding voltage: 500V AC 1 MINUTE.
 - 2.6 Solder ability:245±5℃, 5±0.5s.
 - 2.7 Durability:3000 Cycles Min.
 - 2.8 Operating condition:Temperature-20℃~+85℃; Humidity 80% R.H MAX
 3. MECHANICAL:
 - 3.1 Contact Force:0.2N Min
 4. PLEASE CONTACT KRCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY

5. PART No.:
TF CON. 0 SP - 03 00 08- 16 T
0=WITHOUT POST
SP=SIMPLE TYPE
03:HEIGHT 0.3mm
T=端子接触点防溃设计
16=Product Order
Pin NO. 8=8Pin
00=NORMAL TYPE.(ON PCB)



μSD Block Pin Definition

PIN	NAME
C1	DATA2
C2	CD/DATA3
C3	CMD
C4	VCD
C5	CLK
C6	Vss2
C7	DATA0
C8	DATA1



- RECOMMEND PCB LAYOUT (TOLERANCE ±0.05)
- Soldering Pad area
 - Open wire restricted area (possibly touch of componets on PCB)
 - Connector outline
 - Pad area(only for mechanical function)
 1. Touch area of contact tips, no electrical function and only for mechanical function
 2. Don't brush Tin pasted on the area during SMT process.

②	Housing	1	LCP	COLOUR:BLACK	UL 94V-0
①	Contact	1	COPPER ALLOY	Contact Area: Au 3U"Min, Solder area: Au 1U"Min ; Under plate Ni 50u"Min all over	T=0.08±0.01mm
NO.	PART NAME	QTY	MATERIAL	DESCRIPTION	REMARK
UNLESS OTHERWISE SPECIFIED TOLERANCES			深圳市精睿兴业科技有限公司 SHENZHEN KRCONN TECHNOLOGY CO., LTD		
DECIMALS:			ANGLES:	TITLE 0.3H Micro SD CARD BLOCK CONN.	
X :±0.5			X :±2°	DWN	ALLEN PART NO. T0SP-030008-16T
X.X :±0.20			X.X :±1°	CHKD	KEVIN SCALE:1:1 UNIT: mm
X.XX :±0.10				APVD	ERIC.W SIZE: A3 SHEET:1OF 1 REV: A2
CUSTOMER COPY					

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